

APPROVAL SHEET

MULTILAYER CERAMIC CAPACITORS

Safety Certified X1/Y2, S2 Series

1808 to 2220 Sizes

NP0 & X7R Dielectrics

Halogen Free & RoHS Compliance

*Contents in this sheet are subject to change without prior notice.

1. DESCRIPTION

WTC's SAFETY CERTIFIED CAPACITORS are designed for surge or lightning immunity in modem facsimile and other equipments. The capacitors of series S2 are class X1/Y2 compliant respectively.

The green type capacitors in S2 and S3 series are manufactured by using environmentally friendly materials without lead or cadmium.

The terminations are composed of plated nickel and pure tin to feature the superior leaching resistance during soldering.

2. FEATURES

- a. High reliability and stability.
- b. Small size and high capacitance
- c. RoHS compliant
- d. Safety standard approval by EN 60384-14 : 2013 IEC 60384-14 : 2013 UL 60384-14 (Ed 2.0)
- e. Certificate number:

TUV: R50381780

UL: E182369

HALOGEN compliant.

TÜVRheinland CERTIFIED TÜVRheinland CERTIFIED TÜVRheinland CERTIFIED Www.tuv.com ID 1419048358

3. APPLICATIONS

- a. Modem.
- b. Facsimile.
- c. Telephone.
- d. Other electronic equipment for lighting or surge protection and isolation



4. HOW TO ORDER

<u>S2</u>	<u>42</u>	<u>B</u>	<u>471</u>	<u>K</u>	<u>502</u>	<u>M</u>	I
<u>Series</u>	<u>Size</u>	<u>Dielectric</u>	Capacitance	<u>Tolerance</u>	Impulse voltage	<u>Termination</u>	<u>Packaging</u>
S2=X1/Y2 Safety Certified	42 =1808 (4520) 43 =1812 (4532) 52 =2211 (5728) 55 =2220 (5750)	N =NP0 B =X7R	Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 0R5=0.5pF 1R0=1.0pF 100=10x10 ⁰ =10pF 471=470pF	D= ±0.5pF F= ±1.0%	Two significant digits followed by no. of zeros. And R is in place of decimal point. 502: 5000V Impulse Voltage 602: 6000V Impulse Voltage	E= Soft termination Z= Soft termination + Surface Coating M= Surface Coating (Specific product) K= Non Coating (Specific product)	

5. EXTERNAL DIMENSIONS & STRUCTURE

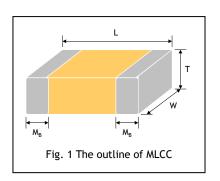
5-1 Safety certified Caps.

Size Inch (mm)	L (mm)	W (mm)	T (mm)	M _B (mm)
1808 (4520)	4.50 +0.8/-0.3	2.00±0.25	1.25±0.10 (D)	0.50±0.25
1812 (4532)	4.50 +0.8/-0.3	3.20±0.40	1.40±0.15 (F) 1.60±0.20 (G)	0.50±0.25
2211 (5728)	5.70±0.40	2.80±0.30	2.00±0.20 (K) 2.50±0.30 (M)	0.60±0.30
2220 (5750)	5.70±0.40	5.00±0.40	2.80±0.30 (U)	0.60±0.30



Size Inch (mm)	L (mm)	W (mm)	T (mm)	M _B (mm)
1808 (4520)	4.50 +0.9/-0.3	2.00±0.30	1.25±0.10 (D)	0.50±0.25
1812 (4532)	4.50 +0.9/-0.3	3.20±0.40	1.40±0.15 (F) 1.60±0.20 (G)	0.50±0.25
2211 (5728)	5.70±0.50	2.80±0.40	2.00±0.20 (K) 2.50±0.30 (M)	0.60±0.30
2220 (5750)	5.70±0.50	5.00±0.50	2.80±0.30 (U)	0.60±0.30

[#] Reflow soldering only is recommended



6. GENERAL ELECTRICAL DATA

Dielectric	NP0	X7R				
Size	1808, 1812, 2211	1808, 1812, 2211, 2220				
Capacitance	3pF to 680pF	100pF to 4700pF				
Capacitance tolerance	Cap.<10pF: C (±0.25pF), D (±0.5pF) Cap.≥10pF: F (±1%), G (±2%), J (±5%), K (±10%), M (±20%)	J (±5%), K (±10%), M (±20%)				
Rated voltage (WVAC)	250Va	ac				
Q/ DF(Tan δ)	FCap<30pF: Q≥400+20C \ce Cap≥30pF: Q≥1000	DF≤2.5%				
Insulation resistance at Ur	≥10G	Ω				
Peak impulse voltage	5000V ~ 6	6000V				
Operating temperature	-55 to +1	25°C				
Capacitance characteristic	±30ppm/°C ±15%					
Termination	Ni/Sn (lead-free termination)					
Certified number	TUV: R50195920, TUV: R50381780, UL: E182369					
Test standard	EN 60384-14 : 2013, IEC 60384-14	1 : 2013, UL 60384-14 (Ed 2.0)				

^{*} NP0: Apply 1.0±0.2Vrms, 1.0MHz±10% for Cap≤1000pF and 1.0±0.2Vrms, 1.0kHz±10% for Cap>1000pF, at 25°C ambient temperature.

7. PACKAGE DIMENSION AND QUANTITY

0:	This large (com)(0		Plasti	c tape
Size	Thickness (mm)/S	ymboi	7" reel	13" reel
	1.40±0.15	F	2k	10k
1808 (4520)	1.60±0.20	G	2k	8k
	2.00±0.20	K	1k	6k
	1.25±0.10	D	1k	5k
1010 (4500)	1.60±0.20	G	1k	4k
1812 (4532)	2.00±0.20	K	1k	3k
	2.50±0.30	М	0.5k	3k
	1.60±0.20	G	1k	4k
2244 (5720)	2.00±0.20	K	1k	3k
2211 (5728)	2.50±0.30	М	0.5k	3k
	2.80±0.30	U	0.5k	-
2220 (5750)	2.00±0.20	K	1k	3k
2220 (5750)	2.50±0.30	М	0.5k	2k

Unit: pieces

^{*} X7R: Apply 1.0±0.2Vrms, 1.0kHz±10%, at 25°C ambient temperature.



8. CAPACITANCE RANGE

- "+" mark: Surface coating is the standard product.
- "-" mark: Non-surface coating is the standard product.

	mark: Non-surface o	boating is the	e staridai	a product.		NP0			
SIZE		180	8	1812		2211		221	1
PEAK IMPULSE VOLTAGE			<u>-</u>	5000				600	
		TUV	UL	TUV	UL	TUV	UL	TUV	UL
	Certificated	IEC60384-14	60384	IEC60384-14	60384	IEC60384-14	60384	IEC60384-14	60384
	3.0pF (3R0)	F ⁻	F ⁻						
	3.3pF (3R3)		F ⁻						
	3.9pF (3R9)		F ⁻						
	4.0pF (4R0)		F ⁻			K ⁻	K ⁻	K ⁻	K ⁻
	4.7pF (4R7)		F ⁻			κ-	K ⁻	κ-	K ⁻
	5.0pF (5R0)	İ	F ⁻			ĸ ⁻	ĸ-	κ-	K ⁻
	5.6pF (5R6)		F ⁻			κ-	ĸ-	κ-	ĸ-
	6.0pF (6R0)	_	F ⁻			κ-	ĸ ⁻	κ-	ĸ-
	6.8pF (6R8)	İ	F ⁻			κ¯	ĸ-	K ⁻	K ⁻
	7.0pF (7R0)		F ⁻			κ¯	ĸ ⁻	κ¯	K ⁻
	8.0pF (8R0)	İ	F ⁻			κ¯	ĸ ⁻	κ¯	ĸ -
	8.2pF (8R2)	_	F ⁻			K ⁻	ĸ-	κ-	ĸ-
	9.0pF (9R0)	F ⁻	F	, +	1-	κ-	ĸ-	κ-	κ¯
	10pF (100)		居日	T/B-	130	κ¯	ĸ-	κ-	K ⁻
	12pF (120)	F	F	2 DI 1/1	D ⁷	κ¯	ĸ ⁻	κ-	ĸ'
	15pF (150)	F /	F.	XXXVI	AD.	K K	ĸ ⁻	κ-	K ⁻
	18pF (180)	F ZZZ	F. K	D ⁻	D -	YK-	ĸ ⁻	κ-	K ⁻
	22pF (220)		F	D ⁻	D ⁻	K ⁻	K ⁻	κ-	K ⁻
Capacitance	27pF (270)		<i>H#</i> // F ⁻	D ⁻	D ⁻	⊒\\ κ⁻	K ⁻	κ-	K ⁻
cita	33pF (330)		F		D ⁻	K ⁻	κ¯	K ⁻	K ⁻
aba	39pF (390)		GASS	EVE SETEM A	TLI DOCE	_ K	κ¯	κ-	ĸ ⁻
Ö	47pF (470)		G G	D ⁻	D ⁻	Ō κ≧	K ⁻	κ -	κ -
	56pF (560)		G ⁻	D ⁻	D ⁻	K	K ⁻	κ-	κ -
	68pF (680)		G G	D ⁻	D_O	K.	K ⁻	M ⁻	M ⁻
	82pF (820)		///G ^T 9/	/ ₂ D	CD.	Ø K-	K ⁻	M ⁻	M ⁻
	100pF (101)	κ-	W.	(Pog)	D.	K K	K ⁻	υ¯	U
	120pF (121)		K-2//	VOLOGY CORP	JEVID2111.	M ⁻	M ⁻		
	130pF (131)		κ-	D	D ⁻	M ⁻	M		
	150pF (151)		κ-	D ⁻	D	M ⁻	M		
	160pF (161)		κ-	D ⁻	D ⁻	M ⁻	M ⁻		
	180pF (181)		κ-	D ⁻	D	M ⁻	M		
	220pF (221)		κ-	K -	K	M ⁻	M ⁻		
	270pF (271)		κ-	K -	K	M ⁻	M ⁻		
	300pF (301)			K -	K	M ⁻	M ⁻		
	330pF (331)			K K	K¯	M ⁻	M ⁻		
	390pF (391)	1		K ⁻	K	M ⁻	M ⁻		
	470pF (471)			K ⁻	K ⁻	M ⁻	M ⁻		
	560pF (561)					M ⁻	M ⁻		
	680pF (681)	1				M ⁻	M ⁻		
	720pF (721)	1							

The letter in cell is expressed the symbol of product thickness.
 For more information about products with special capacitance or other data, please contact WTC local representative.

Multilayer Ceramic Capacitors

- "+" mark: Surface coating is the standard product.
- "-" mark: Non-surface coating is the standard product.

DIELECTRIC					Х7	'R			
	SIZE	1808		1812		2211		2220	
PEAK	(IMPULSE VOLTAGE				50	00			
	Certificated	TUV IEC60384-14	UL 60384	TUV IEC60384-14	UL 60384	TUV IEC60384-14	UL 60384	TUV IEC60384-14	UL 60384
	100pF (101)	G ⁻	G ⁻			G ⁻	G ⁻		
	120pF (121)	G ⁺	G ⁺			G ⁺	G ⁺		
	130pF (131)	G ⁺	G †			G ⁺	G ⁺		
	150pF (151)	G ⁺	G ⁺	G ⁺	G ⁺	G ⁺	G ⁺		
	160pF (161)	G ⁺	G ⁺	G ⁺	G ⁺	G ⁺	G ⁺	K +	K*
	180pF (181)	G ⁺	G ⁺	G ⁺	G +	G ⁺	G ⁺	K ⁺	K*
	220pF (221)	G ⁺	G ⁺	G ⁺	G +	G ⁺	G ⁺	K*	K*
	270pF (271)	K +	K*	G ⁺	G +	G ⁺	G *	K ⁺	K*
	300pF (301)	K +	K +	G ⁺	G *	G ⁺	G †	K ⁺	K +
	330pF (331)	K +	K +	G ⁺	G +	G ⁺	G *	K ⁺	K +
9	390pF (391)	K +	K +	G ⁺	G †	G ⁺	G †	K ⁺	K +
Capacitance	470pF (471)	K ⁺	K +	G ⁺	G †	K ⁺	K ⁺	K ⁺	K ⁺
oaci	560pF (561)	K +	K ⁺	G ⁺	G ⁺	K ⁺	K +	K ⁺	K ⁺
Cal	680pF (681)	K ⁺	K+PIT	K+ /	K ⁺	K ⁺	K ⁺	K ⁺	K ⁺
	720pF (721)	K +	K*	- PK+/2	K [±]	K ⁺	K +	K ⁺	K +
	820pF (821)	K+ /	K+\\	Y-11/K+ / /	K ⁺	K+	K ⁺	K ⁺	K ⁺
	1,000pF (102)	K † ////	K ⁺	M ⁺	M +	72W+	M +	K +	K*
	1,200pF (122)		44,5		<u> </u>	M ⁺	M ⁺	M ⁺	M ⁺
	1,500pF (152)		14/			M ⁺	M ⁺	M ⁺	M ⁺
	1,800pF (182)		PASSIV	E SYSTEM ALL	IANCE	M ⁺	M +	M ⁺	м +
	2,200pF (222)	8		C DIDIEM AL		M ⁺	M+	M ⁺	M ⁺
	2,700pF (272)	PUR	27			D †	U +	M ⁺	M+
	3,300pF (332)	99	0.		36	23		M ⁺	м +
	3,900pF (392)	C	// /0~			23		M ⁺	м +
	4,700pF (472)		1/c/ CP	bologi	0, "16	2		M ⁺	M +

The letter in cell is expressed the symbol of product thickness.
 For more information about products with special capacitance or other data, please contact WTC local representative.



9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	Item	Standard Method	Test Condition	Requirements
	Visual	IEC 60384-1 4.1		* No remarkable defect. * Dimensions to confirm to individual specification sheet.
	•	IEC 60384-1 4.2.2 IEC 60384-1	* Test temp.: Room Temperature. * Class I : (C0G) Cap.≤1000pF, 1.0±0.2Vrms, 1MHz±10%. Cap.>1000pF, 1.0±0.2Vrms, 1KHz±10%.	* Capacitance is within specified tolerance. * C _R means rated capacitance for conform to the E6 series of preferred values given in IEC 60063.
	(Dissipation	4.2.3		Dielectric Q/D.F. Remark
	Factor) Tangent of loos angle		* Class II : (X7R) 1.0±0.2Vrms, 1KHz±10%.	Class I (C0G) Q≥1000 Cap.≥30pF Q≥400+20C Cap.<30pF
				Class II (X7R) D.F.≤2.5%
	Coefficient	IEC 60384-21/22 4.6	With no electrical load. T.C. Operating Temp C0G(NP0) -55~125°C at 25°C X7R -55~125°C at 25°C	T.C. Capacitance Change C0G(NP0) Within ±30ppm/°C X7R Within ±15%
	Voltage proof (Dielectric Strength)	IEC 60384-14 4.2.1	* To apply voltage: X Capacitor: 1075Vdc (4.3U _R). Y Capacitor: 1500Vac. * Duration: 60 sec. * The charge current shall not exceed 0.05A. * The voltage shall be raised from the near zero to the test voltage a rate not exceeding 150V(r.m.s.)/sec.	* No evidence of damage or flash over during test.
6.	Resistance	IEC 60384-21/22 4.5.3	Rated Apply Charge Charge Vol.(V) Voltage Current Time >500 500Vdc ≤50mA 60 sec. *Test temp.: Room Temperature.	Dielectric Requirements Class I (C0G) ≥100GΩ or RxC≥1000Ω-F, whichever is smaller Class II (X7R) ≥10GΩ or RxC≥500Ω-F, whichever is smaller
7.		IEC 60384-21/22 4.10	* Solder temperature: 235±5°C(0201~1210). * Solder temperature: 245±5°C(1808~2225). * Dipping time: 2±0.5 sec.	* 75% min. coverage of all metalized area.
_	Resistance to Soldering	IEC 60384-14	* Solder temperature : 260±5°C. * Dipping time : 10±1 sec.	Dielectric I.R. Cap. Change Q/D.F.
	Heat	IEC 60384-21/22 4.9	* Preheating: 120 to 150°C for 1 minute before immerse the capacitor in a eutectic solder. * Measurement to be made after keeping at room	Class I (C0G) ≥1GΩ Within ±2.5% or ±0.25pF, whichever initial requirements
			temperature for 24±2 hrs.	Class II (X7R) ≥1GΩ Within ±7.5% requireme nt
	Temperature Cycle	IEC 60384-21/22 4.11	* Conduct the five cycles according to the temperatures and time.	
		4.11	Step Temp.(°C) Time(min.) Min. operating 20.00	Dielectric I.R. Cap. Change Q/D.F.
			temp. +0/-3	Class I Within ±2.5% or ±0.25pF,
			2 Room temp. 2~3 Max.operating 30±3	(C0G) To meet whichever is initial requirement
			temp. +3/-0 4 Room temp. 2~3	require ≤1.5(D.F.) ×
			* Measurement to be made after keeping at room temperature for 24±2 hrs.	(X7R) Within ±7.5% initial requirement

^{* &}quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 25 to 75%, Atmospheric pressure: 86 to 106kPa.



Multilayer Ceramic Capacitors

No.	Item	Standard Method	Test Condition		Re	quirements	
10.	Humidity	IEC 60384-14	* Test temp. : 40±2°C.	* No rem	arkable dam	age.	
	(Damp Heat) Steady State	4.12	* Humidity : 90~95% RH. * Test time : 500 +24/-0hrs.	Dielectr ic	I.R.	Cap. Change	Q/D.F.
			 * Applied voltage : 250Vac. * Measurement to be made after keeping at room temp. for 24±2 hrs (Class I) and 48±4 hrs (Class 	Class I (C0G)	≥1GΩ or RxC≥ 25Ω-F,	Within ±3.0% or ±2pF, whichever is larger	≤0.25%
			II).	Class II (X7R)	whichever is smaller	Within ±15%	≤2.0(D.F.) × initial requireme nt
11.	Passive Flammability	IEC 60384-14 4.17 IEC 60384-1 4.38	* Volume sample: 21.56 mm³ * Flame exposure time: 5 sec Max. * Category of flammability : C.	* Capacit	tor didn't bur	n at all.	
12.	Active Flammability	IEC 60384-21/22 4.18	* The capacitors applied UR (250Vac). Then each sample shall be subjected to 20 discharges from a tank capacitor, charge to a voltage that, when discharged, plase Ui 2500V for X1Y2 across the capacitor under test. The interval between		eese cloth sh	nall not burn with a	flame.
13	High	IEC 60384-14	successive discharges shall be 5 sec. * Impulse Voltage:	* Appear	ance :		
	Temperature Load (Endurance)	4.14	Each individual capacitor shall be subjected to a Vp = 5.0KV (X1Y2 Class Impulse 5KV) & Vp = 6.0KV (X1Y2 Class Impulse 6KV) impulse for three times before applied to endurance test. * Test temp.: 125±3°C. * Test time: 1000 +48/-0 hrs. * Applied voltage: X capacitor: 1.25UR (312.5Vac). Y capacitor: 1.70UR (425Vac). Once every hour the voltage shall be increased to 1000Vrms for 0.1 sec. * Measurement to be made after keeping at room temp. for 24±2 hrs (Class I) and 48±4 hrs (Class II).	No mech * Cap. ch COG with X7R with * D.F. va COG≤0.2 X7R≤5.0 * I.R.≥10 * Dielecti value.	anical dama nange: nin ±5% or ±0 in ±20%. lue: 5%. %. GΩ. ric strength s	0.5pF, whichever in the specification of the specif	
14.	Resistance to Flexure of	IEC 60384-21/22	* The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about				
	Substrate	4.8	1mm per second until the deflection becomes:	Dielectri Class I		change ±3.0% or ±2pF, w	hichover is
			1mm for standard termination product, 3mm for soft termination product.	(C0G) Class II	larger	±3.0% or ±2pr, w	nicheveris
			R = 230 R = 230 1mm or 3mm	capacita	ance under s	ange means the cl pecified flexure of measured before	substrate

^{* &}quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 25 to 75%, Atmospheric pressure: 86 to 106kPa.

Multilayer Ceramic Capacitors

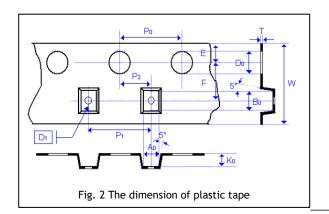
Approval Sheet

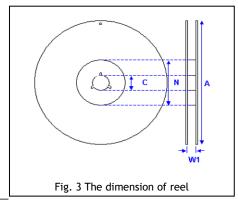
No.	Item	Standard Method	Test Condition	Requirements
15.	Adhesive Strength of Termination	IEC 60384-21/22 4.15 IEC 60384-1 4.13	* Capacitors mounted on a substrate. A force of 10N applied perpendicular to the place of substrate and parallel the line joining the center of terminations for 10±1 sec. Pressurizing force.	
16.	Vibration	IEC 60384-1 4.17	 * Reflow solder the capacitors on P. C. Board before test. * Vibration frequency: 10~55 Hz/min. * Total amplitude: 1.5mm. * Repeat the conditions for 2 hours each in 3 perpendicular directions. 	* No remarkable damage. * Cap. change and Q/D.F. : To meet initial spec.
17.	Impulse Voltage	IEC 60384-14 4.13	* X1 : 4.0KV * Y2 : 5.0KV. * Number of impulse : 24 max.	* There shall be no permanent breakdown or flashover.

^{* &}quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 25 to 75%, Atmospheric pressure: 86 to 106kPa.



EMBOSSED TAPE DIMENSIONS



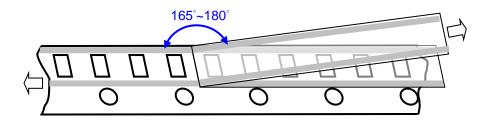


Size	18	08	18	12	22	11	22	20
Chip Thickness	1.25±0.10 1.40±0.15 1.60±0.20	2.00±0.20	1.25±0.10 1.60±0.20 2.00±0.20	2.50±0.30	1.60±0.20 2.00±0.20	2.50±0.30 2.80±0.30	2.00±0.20	2.50±0.30
A_0	<2.50	<2.50	<3.90	<3.90	<3.30	<3.30	<5.80	<5.80
B ₀	<6.00	<6.00	<6.00	<6.00	<6.50	<6.50	<6.50	<6.50
Т	0.25±0.10	0.25±0.10	0.25±0.10	0.25±0.10	0.30±0.10	0.30±0.10	0.30±0.10	0.30±0.10
K ₀	<2.50	<2.50	<2.50	<3.50	<2.50	<3.50	<2.50	<3.50
W	12.0±0.30	12.0±0.30	12.0±0.30	12.0±0.30	12.0±0.30	12.0±0.30	12.0±0.30	12.0±0.30
P_0	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
10xP ₀	40.0±0.20	40.0±0.20	40.00±0.20	40.00±0.20	40.0±0.20	40.0±0.20	40.00±0.20	40.00±0.20
P ₁	4.00±0.10	4.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10
P ₂	2.00±0.10	2.00±0.10	2.00±0.10	2.00±0.10	2.00±0.10	2.00±0.10	2.00±0.10	2.00±0.10
D_0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0
D_1	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10
E	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10
F	5.50±0.10	5.50±0.10	5.50±0.10	5.50±0.10	5.50±0.10	5.50±0.10	5.50±0.10	5.50±0.10

Size	1808, 1812	1808, 1812, 2211, 2220				
Reel size	7"	13"				
С	13.0+0.5/-0.2	13.0+0.5/-0.2				
W_1	12.4+2.0/-0	12.4+2.0/-0				
Α	178.0±1.0	330.0±1.0				
N	60.0+1.0/-0	100±1.0				

■ Peeling force (EIA-481)

Peel-off force should be in the range of 10 grams to 100 grams at a peel-off speed of 300±10 mm/min.



APPLICATION NOTES

Storage

To prevent the damage of solderability of terminations, the following storage conditions are recommended: Indoors under 5 ~ 40°C and 20% ~ 70% RH; MSL Level 1.

No harmful gases containing sulfuric acid, ammonia, hydrogen sulfide or chlorine.

Packaging should not be opened until the capacitors are required for use. If opened, the pack should be re-sealed as soon as is practicable. Taped product should be stored out of direct sunlight, which might promote deterioration in tape or adhesion performance. The product is recommended to be used within 12 months after shipment and checked the solderability before use.

Handling

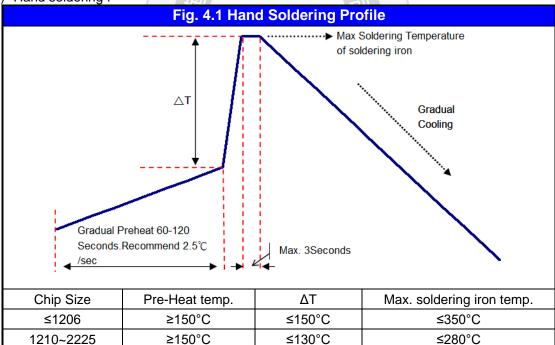
Chip capacitors are dense, hard, brittle, and abrasive materials. They are liable to suffer mechanical damage, in the form of cracks or chips. Chip Capacitors should be handled with care to avoid contamination or damage. To use vacuum or plastic tweezers to pick up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

In order to minimize the risk of thermal shock during soldering, a carefully controlled preheat is required. The rate of preheat should not exceed 3°C per second.

Soldering

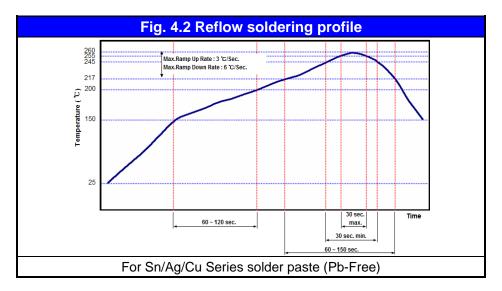
Use middy activated rosin RA and RMA fluxes do not use activated flux. The amount of solder in each solder joint should be controlled to prevent the damage of chip capacitors caused by the stress between solder, chips, and substrate.

a.) Hand soldering:



- * Soldering iron tip diameter ≤1.0 mm and wattage max. 20W.
- * The Capacitors shall be pre-heated and that the temperature gradient between the devices and the tip of the soldering iron.
- * The required amount of solder shall be melted on the soldering tip.
- * The tip of iron should not contact the ceramic body directly.
- * The Capacitors shall be cooled gradually at room temperature after soldering.
- * Forced air cooling is not allowed.

b.) Reflow soldering:



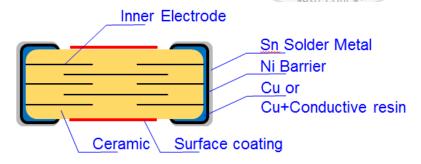
Cooling

After soldering, cool the chips and the substrate gradually to room temperature. Natural cooling in air is recommended to minimize stress in the solder joint.

Cleaning

All flux residues must be removed by using suitable electronic-grade vapor-cleaning solvents to eliminate contamination that could cause electrolytic surface corrosion. Good results can be obtained by using ultrasonic cleaning of the solvent. The choice of the proper system is depends upon many factors such as component mix, flux, and solder paste and assembly method. The ability of the cleaning system to remove flux residues and contamination from under the chips is very important.

Constructions





FOOTPRINT DIMENSIONS

Size Inch (mm)	Item	Dimension (mm)	Fig. 9.4 Illustration of Footprint
1808(4520)	D1	6.40~7.50	
	D2	1.45~1.75	
	D3	3.50~4.00	
	D4	1.45~1.75	
	D5	1.80~2.00	
1812(4532)	D1	6.40~7.50	
	D2	1.45~1.75	D2
	D3	3.50~4.00	_ +
	D4	1.45~1.75	D1 D3
	D5	2.50~2.80	
2211(5728)	D1	7.80	D4
	D2	1.75	
	D3	4.30	
	D4	1.75	—▶ D5
	D5	2.50	
2220(5750)	D1	7.80	Dimensions in millimeters
	D2	21.75	3
	D3	4.30	7.36
	D4 /\	4.75 分分を	7 21
	D5 4V	4.60	/A / A

